WORLD OF

Organized by



Supported by:

U.S. Department of Commerce; SiC Alliance; Japan LED Association; Japan Institute of Electronics Packaging; The Japan Society of Applied Physics; Japan Electronics and Information Technology Industries Association; The Japanese Liquid Crystal Society; The Vacuum Society of Japan; Japan Vacuum Industry Association; Japan Electronics Packaging and Circuits Association; Nippon Electronic Device Industry Association; Semiconductor Equipment Association Japan; Japan Venture Capital Association

Registers Now ▶▶▶ www.semiconjapan.org

DREAMS START HERE

CONNECT | COLLABORATE | INNOVATE













SEMICON Japan 2017 Sponsors (in alphabetical order)

As of Oct. 1st

Platinum Sponsors

Gold Sponsors

Hitachi High-Tech























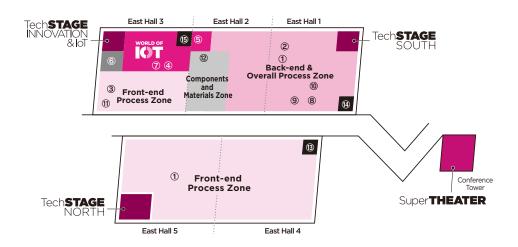








DREAMS START HERE



Comprehensive Coverage

Explore exhibits that cover the entire device manufacturing processes in three zones; Front-end Process, Back-end & Overall Process, and Components & Materials, along with the following theme pavilions:

- · Manufacturing Innovation Pavilion (Map(1)) Mid-to-small size companies and newcomers
- Secondary Equipment and Services Pavilion (Map 2) Secondary equipment market that fuels 200 mm fab capacity
- Minimalfab Pavilion (Map 3) Minimal Fab General Incorporated Association members
- · Compound Semiconductor Pavilion (Map4) SiC, GaN, Ga2O3 technologies

Regional Pavilions

- US Pavilion (Map(7))
- Holland Pavilion (Map®)
- German Pavilion (Map[®])
- Moscow Pavilion (Map[®])
- TOHOKU Pavilion (Map(1))
- Kyusyu Pavilion (Map[®])



Sponsored by





The World of IoT is a showcase for IoT applications and enabling technologies. The growth of IoT applications present new opportunities for the entire semiconductor manufacturing supply chain.

Follow SEMICON Japan on SNS



SEMI Presents

"All about Drones"

Learn about drone technology and business through:

- 1. A tear-down drone exhibit
- 2 Drone lectures
- 3. Fly a drone by yourself!



Meet startups through pitch presentations and exhibits that bring new ideas to our industry. Pitch presentation will be on December 14 (see page 3).



Sponsored by

HORIBA

(Map(5))

(Map(6))

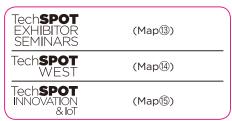
rnuratec

Students and young engineers bring our industry into the future. SEMI presents the GAKKO (school) program to help their growth and engagements.

- TECH CAMP@GAKKO Hackathon based program
- ACADEMIA@GAKKO University and institute exhibits
- MIRAI COLLEGE@GAKKO Career guidance to university students
- MIRAI PROGRAM@GAKKO Lectures for students and young engineers
- THE KOSEN@GAKKO Exhibits by technical college students
- **INNOVATE** Reception A reception for students and young engineers

Show Floor Events

Exhibitor Presentations



Networking Events

SEMICON Japan Happy Hour

Date/Time • Dec. 14 / 16:00-17:00 Venue • Participating exhibitor booths Join select exhibitors during this hospitality event. Engage and network in a relaxed environment.

INNOVATE Reception (Invitation Only)

Date/Time • Dec. 14 / 17:00-18:00 Venue • INNOVATION Lounge, East Hall 3 A special networking opportunity for WORLD OF IOT and INNOVATION VILLAGE participants and visiting young engineers.

Conference Tower Events

SEMI Presidents Reception Paid event

Date/Time • Dec. 13 / 17:15-18:30

Venue • Reception Hall B, Conference Tower 1F The SEMI Presidents Reception is an ideal opportunity for semiconductor manufacturers and executives from equipment and materials companies to get together and network on a global scale.

SEMI Standards Awards Ceremony and Friendship Party

Free

Date/Time • Dec. 14 / 17:30-19:00 Venue • Room 607, Conference Tower 6F SEMI Standards members from around the world ioin to network and celebrate our achievements together, including presentation of the SEMI Standards Awards

SEMI Standards Meetings

Free

Date/Time • Dec. 13-15 / 8:00-17:00 Venue • Rooms on Conference Tower 6&7F SEMI Standards are used extensively around the world in the microelectronics manufacturing. Any registered SEMI Standards member may participate in the meetings.

Partner Event

ISSM 2017 Strategic Forum

"Awaking 6 inch and 8 inch fabs"

Date/Time • Dec. 13 / 13:00-17:30 Venue • Room 9-A, TFT Hall

Driven by the growing sensor market for IoT devices, automotive and smartphones, 200 mm fab demands are increasing and prolonging fab life is an issue. This forum will discuss the innovative production engineering for legacy fabs.

Exhibitor Search Tool

The Exhibitor Search engine will be available through the SEMICON Japan website in November to help plan your visit with detailed exhibitor information.

Free



Free

Wed., Dec. 13

10:20-12:00

Heterogeneous Integration Roadmap

With the completion of the ITRS, the IEEE CPMT Society, the Electron Device Society, the Photonics Society, the ASME EPPD Division, and SEMI now present the "Heterogeneous Integration Roadmap". The session introduces its latest developments.

12:50-14:30

SCIS Forum

Sub-components - One of the Last Frontiers to Enabling Yields for Advanced Nodes

This forum will share the ideas and efforts of device manufacturers (IDM), equipment and parts suppliers to deal with the influence of defects caused by manufacturing equipment parts.

15:10-16:50

CGMG Forum

Expanding the World of Material Technologies

Use of AI and big data analysis greatly change the world of material development. This session focuses on the semiconductor market and the future possibilities of material technologies from the material industry viewpoint.

Thu., Dec. 14

10:20-12:00

Challenges of Young Engineers

MIRAI PROGRAM@GAKKO

Young engineers working at the cutting edge of technological research and development fields will talk about their experiences and approaches to their work.

12:50-14:30

STS Packaging Session (1)

Fan-out Wafer Level Packaging Technologies

In this session, experts in assembly, test, and materials will present the latest examples of FOWLP technology development in each area.

15:10-16:50

STS Packaging Session (2)

Packaging Technologies for 3D, Heterogeneous Integration and Automotive

The generation change of packaging technologies is progressing silently yet steadily. In this session, cutting-edge technologies including 3D packaging, heterogeneous integration, automotive semiconductors and sensor packaging will be presented.

Fri., Dec. 15

10:20-12:00

Overview of Semiconductor Device Fabrication Process

MIRAI PROGRAM@GAKKO

Presented by SEMI, this session will cover the key features of semiconductor production technology, as well as the challenges facing cutting-edge technologies.

12:50-14:30

STS Test Session

Quality and Cost Challenges for Connected Devices

In the IoT era, multiple devices and technologies will connect through expanding networks. Speakers at this session will discuss the quality and cost of semiconductor testing that boosts these connections.

15:10-16:50

TECH CAMP Hackathon Presentation

Innovations for a Successful Industry in 10 Years

Young engineers will have the opportunity to interact and communicate broadly with a wide variety of people who they can only meet at SEMICON Japan. They share a new value gained in their realizations and findings.



Wed., Dec. 13

10:20-12:00

STS Special Session -AI-

Innovation of AI Technology for Its Implementation

Evolution of AI technology is steadily progressing for its practical application; At this STS Special Session, leading researchers will provide an overview of various initiatives on the practical application of AI.

12:50-14:30

Smart Healthcare Forum

Healthcare and Society Evolving by AI & IoT

Combining and utilizing both IoT and AI has fostered steady innovation in the medical field. This session will explore the development of medical electronics and the latest technologies and solutions brought by IoT and AI.

15:10-16:50

Smart Mobility Forum

Future Oriented Society and Mobility

From smartphones to smart cars, mobility is driving innovation in electronics, which are in turn driving innovations in mobility. In this forum, experts from leading technology companies will focus on these technologies and how they are shaping our future mobile society.

Thu., Dec. 14

10:20-12:00

Smart Manufacturing Forum

Line Building of Discrete Manufacturing in IoT Era

This session will discuss how to construct an "Autonomous Manufacturing Line" that will be required to establish integrated manufacturing environment which cooperates beyond business boundary in the Industry 4.0 generation.

12:50-14:30

INNOVATION VILLAGE Pitches (1)

Start-Up Presentations

Start-up companies participating in the INNOVATION VILLAGE will present their ideas, technologies, products, and services in short, five-minutes pitches.

15:10-16:50

INNOVATION VILLAGE Pitches (2)

Start-Up Presentations

Continued: Start-up companies participating in the INNOVATION VILLAGE will present their ideas, technologies, products, and services in short, five-minutes pitches.

Fri., Dec. 15

10:20-12:00

IoT Connectivity Forum

5G? LPWA? What is the Next Wireless Communication Technology of Industrial IoT?

In this session, presenters will discuss the connectivity innovations needed to accelerate the Industrial Internet of Things and Smart Manufacturing.

12:50-14:30

STS MEMS/Sensor Session (1)

MEMS Technologies for Autonomous Cars

Assisted and autonomous driving systems rely heavily on advanced MEMS and non-MEMS sensor devices for safety, automation, and control. In this session, presenters will discuss the current state and future of these technologies for smart transportation applications.

15:10-16:50

STS MEMS/Sensor Session (2)

MEMS Devices Enhancing IoT

Advanced MEMS and non-MEMS sensor devices are critical to multiple commercial and consumer IoT applications. In this session, presenters will explore the current and future uses of MEMS and sensors in advancing IoT technologies.



Free

Wed., Dec. 13

10:20-12:00

FHE Session

JPCA/SEMI Collaboration

Flexible Hybrid Electronics (FHE) are making electronics more mobile, more flexible, and more diverse. Discover the latest trends and applications for FHE at this session, co-sponsored by the Japan Electronics Packaging and Circuits Association (JPCA).

12:50-14:30

STS Power Device Session (1)

Wide Band Gap Power Devices -GaN/SiC/GaOx-

Full-scale practical applications of new material power devices has begun. This session will explore the latest technology and market trends for power devices, including SiC, GaN, and GaOx.

15:10-16:50

STS Power Device Session (2)

Wide Band Gap Power Devices -GaN/SiC/GaOx-

Continued: Full-scale practical applications of new material power devices has begun. This session will explore the latest technology and market trends for power devices, including SiC, GaN, and GaOx.

Thu., Dec. 14

10:20-12:00

Sustainable Manufacturing / High Tech Facility Forum

Improve Recycle Rate and Make It Valuable

Improving recycling of materials and resources is critical to sustainable manufacturing. This session will explore how companies are managing materials recycling (including gas and water) and the technologies being employed for improving recycling.

12:50-14:30

STS Advanced Lithography Session (1)

Readiness of EUV Lithography for High Volume Manufacturing

This session will address the ongoing issues and technologies employed in ramping EUV lithography to full production, including materials and light source.

15:10-16:50

STS Advanced Lithography Session (2)

Emerging Patterning Technology and Related Metrology

The presenters will share the latest on topics including multielectron beam exposure technology, nano-imprinting, and pattern measurement technologies.

Fri., Dec. 15

10:20-12:00

Semiconductor Secondary Equipment Business Seminar

New Trends of Secondary Equipment Market in IoT and Connected World

In this session, presenters will give an update of the Chinese secondary equipment market (200mm/300mm) and discuss the increasing demands for 200mm equipment being driven by the growing IoT market.

12:50-14:30

STS Advanced Device Session (1)

Future Vision for Advanced Device 1

In this session, front-line engineers will present the latest technology trends for logic, memory and image sensor devices required for smaller, but higher performing mobile and IoT devices.

15:10-16:50

STS Advanced Device Session (2)

Future Vision for Advanced Device 2

Continued: In this session, front-line engineers will present the latest technology trends for logic, memory and image sensor devices required for smaller, but higher performing mobile and IoT devices.

semi

SuperTHEATER

Wed., Dec. 13

9:40-10:10

Opening Ceremony

10:20-12:00

Opening Keynotes

Visions of the Game Changing Era

IoT and AI are changing the game and redrawing the global industrial map. Technology leaders from SoftBank and Qualcomm —two companies helping drive these changes— will share their visions of the future.



Ken Miyauchi President & CEO SoftBank Corp.

Raj Talluri Senior Vice President of Product Management Qualcomm Technologies, Inc.



Thu., Dec. 14

IT/AI Forum (supported by US Commercial Service)

This popular forum, presented in cooperation with the

US Commercial Service, will focus on disruptive technologies and AI, with speakers exploring the

challenges and opportunities presented by these

Principal Solution Architect

Amazon Web Services, Inc.

Kenzaburo Tamaru

IoT Global Trend Forum

"smarter" and more connected world.

ARM K.K.

Sony Corp.

15:10-16:50

Yuzuru Utsumi

Keiichiro Shimada

Corporate Executive

IoT Key Technology Forum

Dawn of the Smart Automotive Era

innovative solutions that will get us there.

Hideki Mukuno

General Manager

Haruyoshi Kumura

Fellow Nissan Motor Co., Ltd.

Mid-to-Long term Technology,

Corporate Technology Policy and Relations

Technologies for autonomous and electric vehicles must

have security and safety as a top priority as people's lives

depend on that technology being fail-safe. At this session,

executives from leading technology companies focused

on "smart" transportation technology will share their

perspectives on the future of smart cars and the

National Technology Officer

Microsoft Japan Co., Ltd.

Super IoT World Realized by Semiconductor

Semiconductors lie at the heart of all IoT devices, which

means advanced semiconductors are critical to the

growth and connectivity of an IoT future. Executives from

the world's leading technology companies will discuss

the future technology development needed to reach a

Intel Architecture Technology Group

Hideaki Doki

Director

Intel K.K.

Toru Baji

Technology Adviser, GPU Evangelist

NVIDIA Corp

Akira Shibata

Chief Data Scientist, Ph.D. in Physics

DataRobot Japan

Al Strategy by IT Top Runners from the US

Guy Ernest

10:20-12:00

technologies.

12:50-14:30

12:50-14:30

Semiconductor Executive Forum

Growth Strategy in New Business Environment

In this forum, top executives from the semiconductor manufacturing industry will share their perspectives on growth in today's "new business" environment.



Russell Ellwanger Chairman, TowerJazz Panasonic Semiconductor CEO, TowerJazz Semiconductor; Tower Jazz Panasonic Semiconductor Co. Ltd.





Senior VP of Global Manufacturing Global Manufacturing Micron Technology, Inc.

15:10-16:50

SEMI Market Forum

In the Light and Shadow of Awaking China

The semiconductor supply chain market is experiencing a period of very strong growth, especially driven by powerful investments in China for memory and foundry manufacturing. This forum will provide forecasts and insights to help you to develop business strategies for the future in the light and shadow of China's semiconductor industry.



Lung Chu President SEMI China

How to Register

www.semiconiapan.org

Please visit

ter via the website.









Tokyo Big Sight Access Information

Production Technology Development Div. Global MONOZUKURI Management Div

Hitachi Automotive Systems, Ltd.

- Tokyo Waterfront Area Rapid Transit, Rinkai Line, get off at the Kokusai Tenjijo Station, 7 min. walk
- · New Transit System, Yurikamome, get off at the Kokusai-tenjijo-seimon Station, 3 min. walk

By limousine bus from the airport

Approx. 60 minutes from Narita Airport (get off at Tokyo Bay Ariake Washington Hotel, 3 min. walk)

· Approx. 25 minutes from Haneda Airport (get off at Tokyo Big Sight) www.bigsight.jp

Venue: Reception Hall A, Conference Tower 1F, Tokyo Big Sight

Fri., Dec. 15

10:20-12:00

Manufacturing Innovation Forum

Manufacturing Technology for the Diversified Future

Japanese-English Interpretation Available

Leading executives from global manufacturing equipment and fabless companies will share their perspectives on the future of breakthrough technologies and growth strategies for diversifying semiconductor production.



Tetsuro Higashi Corporate Ādvisor, Corporate Tokyo Electron Limited

Jonathan Chang Senior Director Foundry Technology Xilinx, Inc



Rick Gottscho Executive Vice President, Corporate Chief Technology Officer Lam Research Corp.

12:50-14:30

Electronics Trend Forum

New Technologies and Trends that Accelerate the "SMART" Society

Executive leaders from innovative technology companies will share their perspectives on the growing trends in "smart" technologies and what's driving their explosive growth.



Kazuo Kaiimoto Group-wide CTO Office Senior Councillor of Group-wide Software Strategy Panasonic Corp.

Antun Domic Synopsys, Inc



Taro Shimada Senior Executive Operating Officer, Division Lead Japan Digital Factory / Process Industries and Drives Division Siemens K.K.

15:10-16:50

Mirai Vision Forum

A Far Future Brought to You by the Evolved Technologies

How will cloud computing, AI, robots, and green computing change our lives in the future? What are the exciting technologies that are both human- and earthfriendly? This closing forum will provide insight to the world these evolving technologies may bring. Don't miss this SuperTHEATER finale!



Naomi Tomita President & CEO hapi-robo st. Inc

Hironori Kasahara IEEE Computer Society President 2018; Professor, Department of Computer Science and Engineering Director, Advanced Multicore



Henri Tervonen CTO and Head of R&D Foundation Mobile Networks Nokia Corp.



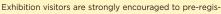


Hotel

Hotels in the vicinity of Tokyo Big Sight can be reserved at special reduced rates.

Inquiries/Application

JTB Global Marketing & Travel SEMICON Japan 2017 JTB Desk Tel: +81-3-5796-5446 Email: semicon2017@gmt.jtb.jp



Pre-registration is required for all sessions and events.

Inquiries SEMICON Japan Executive Secretariat Tel: +81-50-5804-1281

Email: semicon2017@sakurain.co.jp Open: 9:30-17:00 weekdays (excluding 12:00-13:00)